

Vishay Siliconix

Dual N-Channel 60 V (D-S) MOSFET



Marking code: G3

PRODUCT SUMMARY						
V _{DS} (V)	60					
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 10 \text{ V}$	0.0409					
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 4.5 \text{ V}$	0.0516					
Q _g typ. (nC)	2.4					
I _D (A) ^d	6.1					
Configuration	Dual					

FEATURES

- TrenchFET® power MOSFET
- 100 % R_g tested

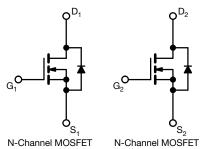




ROHS COMPLIANT HALOGEN FREE

APPLICATIONS

- DC/DC converter
- · Load switch
- Inverters
- Circuit protection



ORDERING INFORMATION	
Package	SO-8
Lead (Pb)-free and halogen-free	Si4946CDY-T1-GE3

PARAMETER Drain-source voltage Gate-source voltage		SYMBOL	LIMIT	UNIT
		V _{DS}	60 ± 20	
		V _{GS}		v
	T _C = 25 °C		6.1	
Continuous dusin surrent /T 150 °C)	T _C = 70 °C		4.9	
Continuous drain current (T _J = 150 °C)	T _A = 25 °C	l _D	5.2 ^{a, b}	
	T _A = 70 °C		4.2 ^{a, b}	•
Pulsed drain current (t = 100 μs)		I _{DM}	25	Α
Continuous source-drain diode current	T _C = 25 °C		2.3	
	T _A = 25 °C	I _S	1.7 ^{a, b}	
Single pulse avalanche current	1 0.1 ml l	I _{AS}	8	
Single pulse avalanche energy	L = 0.1 mH	E _{AS}	3.2	mJ
Maximum power dissipation	T _C = 25 °C		2.8	
	T _C = 70 °C		1.8	14/
	T _A = 25 °C	P _D	2 ^{a, b}	W
	T _A = 70 °C		1.3 ^{a, b}	
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C

THERMAL RESISTANCE RATINGS							
PARAMETER	SYMBOL	TYPICAL	MAXIMUM	UNIT			
Maximum junction-to-ambient a, c	t ≤ 10 s	R _{thJA}	58	62.5	°C/W		
Maximum junction-to-foot (drain)	Steady state	R_{thJF}	38	45	C/VV		

Notes

- a. Surface mounted on 1" x 1" FR4 board
- b. t = 10 s
- c. Maximum under steady state conditions is 110 °C/W
- d. $T_C = 25$ °C



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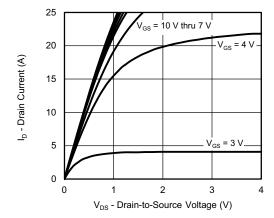
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static				•	•		
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	J 050 A	-	40	-		
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA	ī	-4.8	-	mV/°C	
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	1	-	3	V	
Gate-source leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA	
	I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V	-	-	1	μА	
Zero gate voltage drain current		$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 70 ^{\circ}\text{C}$	-	-	10		
On-state drain current ^a	I _{D(on)}	$V_{DS} \le 10 \text{ V}, V_{GS} = 10 \text{ V}$	8	-	-	Α	
Drain actives on state registeres 3	Б	$V_{GS} = 10 \text{ V}, I_D = 5.2 \text{ A}$	-	0.0330	0.0409	Ω	
Drain-source on-state resistance ^a	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 4.6 A	-	0.0430	0.0516		
Forward transconductance ^a	9 _{fs}	$V_{DS} = 30 \text{ V}, I_D = 5.2 \text{ A}$	-	17	-	S	
Dynamic ^b				•	•		
Input capacitance	C _{iss}		-	350	-	pF	
Output capacitance	C _{oss}	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	148	-		
Reverse transfer capacitance	C _{rss}		-	9	-		
Tabel and a share a	Qg	$V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 5.2 \text{ A}$	-	5.1	10	nC	
Total gate charge			-	2.4	4.8		
Gate-source charge	Q _{gs}	$V_{DS} = 30 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 5.2 \text{ A}$	-	1.1	-		
Gate-drain charge	Q_{gd}		-	0.5	-		
Gate resistance	R_g	f = 1 MHz	0.26	1.3	2.6	Ω	
Turn-on delay time	t _{d(on)}		-	8	16		
Rise time	t _r	$V_{DD}=30~V,~R_L=7.2~\Omega,~I_D\cong4.2~A,$	-	5	10	1	
Turn-off delay time	t _{d(off)}	V_{GEN} = 10 V, R_g = 1 Ω	-	16	30		
Fall time	t _f		-	3	6	1	
Turn-on delay time	t _{d(on)}		=	17	30	ns	
Rise time	t _r	V_{DD} = 30 V, R_L = 7.2 Ω , I_D \cong 4.2 A,	=.	35	55		
Turn-off delay time	t _{d(off)}	V_{GEN} = 4.5 V, R_g = 1 Ω	-	14	28		
Fall time	t _f		-	20	33		
Drain-Source Body Diode Characteristi	cs						
Continuous source-drain diode current	Is	T _C = 25 °C	-	-	2.3		
Pulse diode forward current	I _{SM}		-	-	25	A	
Body diode voltage	V_{SD}	$I_S = 4.2 \text{ A}, V_{GS} = 0 \text{ V}$	-	0.85	1.2	V	
Body diode reverse recovery time	t _{rr}		-	21	32	ns	
Body diode reverse recovery charge	Q_{rr}	1 4 0 A di/dt 100 A/v. T 05 00	-	12	35	nC	
Reverse recovery fall time	t _a	$I_F = 4.2 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$	-	12	-		
Reverse recovery rise time	t _b		-	9	-	ns	

Notes

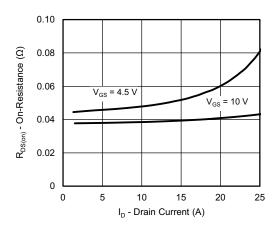
- a. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%$
- b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

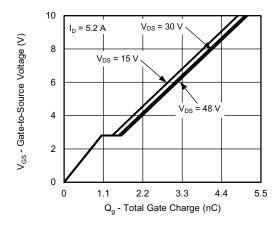




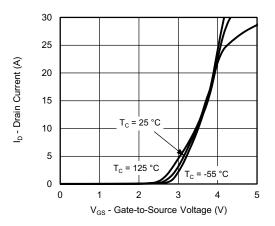
Output Characteristics



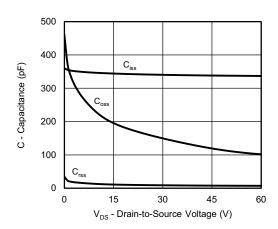
On-Resistance vs. Drain Current and Gate Voltage



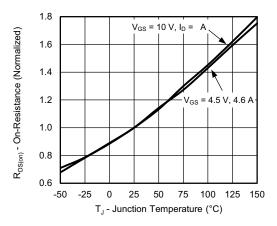
Gate Charge



Transfer Characteristics

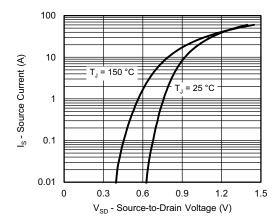


Capacitance

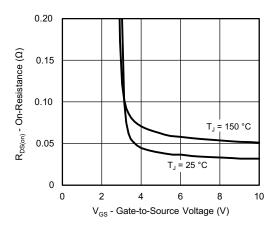


On-Resistance vs. Junction Temperature

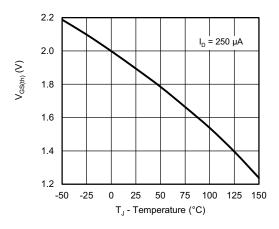




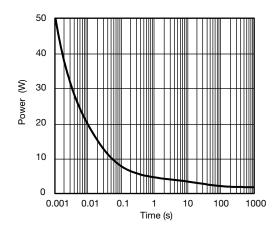
Source-Drain Diode Forward Voltage



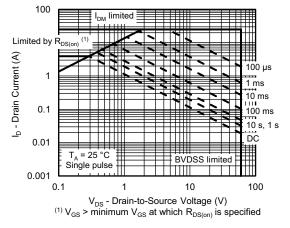
On-Resistance vs. Gate-to-Source Voltage



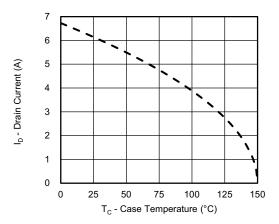
Threshold Voltage



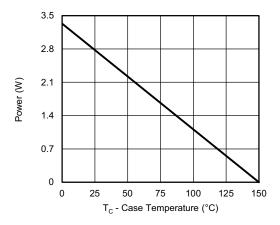
Single Pulse Power, Junction-to-Ambient



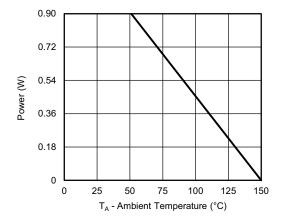
Safe Operating Area, Junction-to-Ambient



Current Derating a



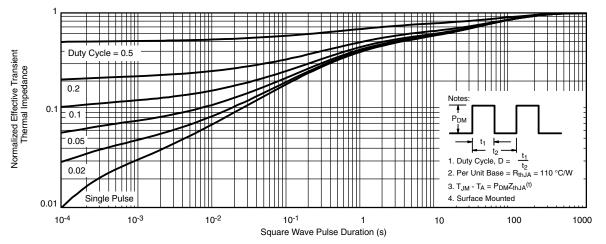




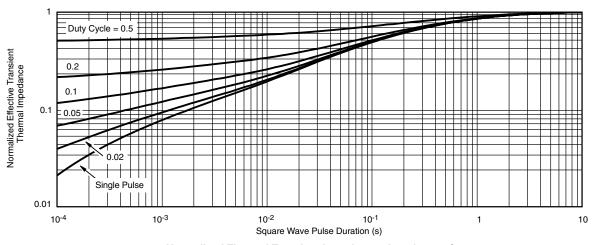
Power, Junction-to-Ambient

a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit





Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?75642.



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







	MILLIM	IETERS	INC	INCHES		
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
Е	3.80	4.00	0.150	0.157		
е	1.27	BSC	0.050 BSC			
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Rev. I. 11-Sep-06						

DWG: 5498

Document Number: 71192 www.vishay.com 11-Sep-06



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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